

STRUCTURE Silicon Monolithic Integrated Circuit

PRODUCT NAME γ -correction IC for TFT-LCD Panel

TYPE **B D 8 1 3 2 F V**

FEATURES Built-in 10bit X 18 Channel γ -correction outputs
 Built-in 10bit X 1 Channel common amplifier

● ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

PARAMETER	SYMBOL	LIMITS	UNIT
Power Supply Voltage 1	DVCC	7	V
Power Supply Voltage 2	VCC	20	V
REFIN Voltage	REF	20	V
Amplifier Drive Current	Io	50*1	mA
Junction Temperature	Tjmax	150	°C
Power Dissipation	Pd	1125*2	mW
Operating Temperature Range	Topr	-30~+85	°C
Storage Temperature Range	Tstg	-55~+150	°C

*1 Do not however exceed Pd.

*2 Pd decreased at 9mV/°C for temperatures above Ta=25°C, mounted on 70×70×1.6mm Glass-epoxy PCB.

● OPERATING CONDITIONS (Ta=-30°C ~+85°C)

PARAMETER	SYMBOL	MIN	MAX	UNIT
Power Supply Voltage 1	DVCC	2.3	4.0	V
Power Supply Voltage 2	VCC	6	18	V
REFIN Voltage	REF	6	18	V
Amplifier Drive Current	Io	-	40	mA
Serial CLK Frequency	fCLK	-	5	MHZ
OSC Frequency	fosc	10	200	KHz

★This product is not designed for protection against radioactive rays.

★The product described in this specification is a strategic product (and/or Service) subject to COCOM regulations. It should not be exported without Authorization from the appropriate government.

Status of this document

The Japanese version of this document is the formal specification.

A customer may use this translation version only for a reference to help reading the formal version.

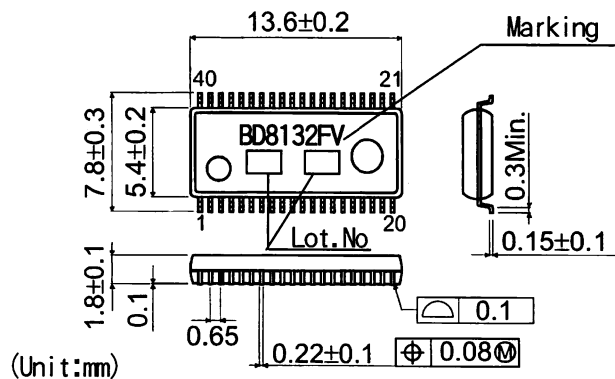
If there are any differences in translation version of this document, formal version takes priority.

●ELECTRICAL CHARACTERISTICS (Unless otherwise specified VCC=15V, DVCC=3.3V, Ta=25°C)

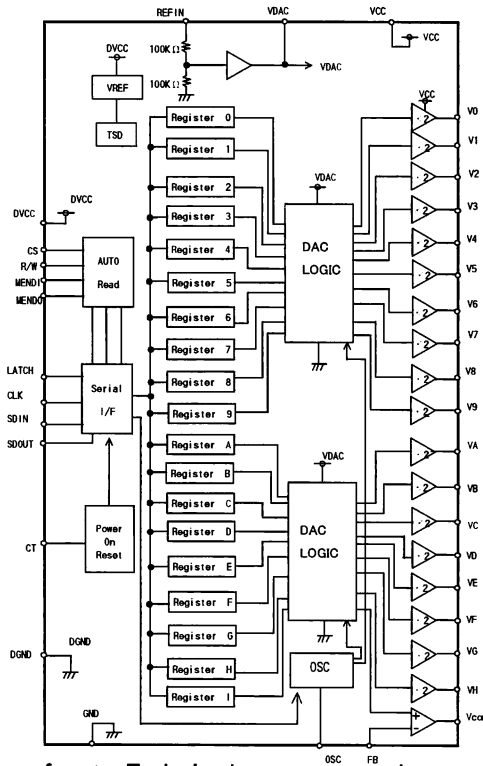
PARAMETER	SYMBOL	LIMIT			UNIT	CONDITIONS
		MIN	TYP	MAX		
【 REFIN 】						
Sink Current	I _{REF}	25	50	75	μA	REF=10V
【 γ-CORRECTION AMP】						
Drive Current	I _o	150	300	-	mA	DAC=3V, OUTx=0V
Load Regulation	ΔV	-	5	20	mV	I _o =+10mA ~ -10mA, OUTx=6V
Slew Rate	SR	-	3.5	-	V/μs	R _o =100KΩ, C _o =100pF ※
Output Voltage High	V _{OH}	VCC-0.16	VCC-0.1	-	V	I _o =-5mA
Output Voltage Low	V _{OL}	-	0.15	0.24	V	I _o =-5mA
【 COMMON AMP 】						
Input Bias Current	I _b	-	0	1	μA	VFB=6V
Drive Current	I _o	150	300	-	mA	DAC=3V, OUTx=0V
Load Regulation	ΔV	-	5	20	mV	I _o =+10mA ~ -10mA, OUTx=3V
Slew Rate	SR	-	3.5	-	V/μs	R _o =100KΩ, C _o =100pF ※
Input Voltage Range	VFB	0	-	VDAC	V	R _o =100KΩ, C _o =100pF ※
Output Voltage high	V _{OH}	VCC-0.16	VCC-0.1	-	V	I _o =-5mA
Output voltage Low	V _{OL}	-	0.15	0.24	V	I _o =-5mA
【 DAC 】						
Resolution Coding	Res	-	10	-	Bit	
Non-Linear Error	LE	-2	-	2	LSB	Error with ideal straight Range 00A~3F5
Differential Error	DLE	-2	-	2	LSB	Error with ideal amount of Increase in 1LSB Range 00A~3F5
【 OSC 】						
Frequency	f _{osc}	-	80	-	KHz	Internal oscillator mode
【 CONTROL SIGNAL 】						
Sink Current	I _{ctL}	-	16	25	μA	
Threshold Voltage	V _{TH}	0.7	-	2.6	V	DVCC=3.3V
Reset Time	tr _{st}	-	45	-	μs	CCT=1000pF
【 WHOLE DEVICE 】						
Circuit Current	I _{cc}	-	20	-	mA	All outputs = 5V

※Design Guarantee (Outgoing inspection is not done all products.)

●PHYSICAL DIMENSION • MARKING (SSOP-B40)



●BLOCK DIAGRAM



*Please refer to Technical note concerning application circuit, and etc.

●PIN NO. & FUNCTION TABLE

PIN No	PIN NAME	Function	PIN No	PIN NAME	Function
1	LATCH	LATCH signal input	21	FB	COM -input
2	SDIN	DATA signal input	22	Vcom	COM output
3	CLK	CLK signal input	23	VH	Gamma H output
4	SDOUT	DATA signal output	24	VG	Gamma G output
5	GND	Ground	25	VF	Gamma F output
6	R/W	Automatic Read ON/OFF input (ON=L, OFF=H)	26	VE	Gamma E output
7	CS	Chip Select signal output	27	VD	Gamma D output
8	MEMDO	External Memory DATA output	28	VC	Gamma C output
9	MEMDI	External Memory DATA input	29	VB	Gamma B output
10	OSC	Synchronized clock inout	30	VA	Gamma A output
11	DVCC	Digital Power Supply	31	V9	Gamma 9 output
12	NC	—	32	V8	Gamma 8 output
13	VCC	Power Supply for Gamma 0~9	33	V7	Gamma 7 output
14	VCC	Power Supply for Gamma A~H, COM, REG	34	V6	Gamma 6 output
15	REFIN	DAC reference input	35	V5	Gamma 5 output
16	VDAC	DAC Voltage output	36	V4	Gamma 4 output
17	CT	Capacitor connection for Power on Reset	37	V3	Gamma 3 output
18	DGND	Ground for DAC	38	V2	Gamma 2 output
19	GND	Ground	39	V1	Gamma 1 output
20	GND	Ground	40	V0	Gamma 0 output

●Operation Notes

1. Absolute maximum range

This product are produced with strict quality control, but might be destroyed in using beyond absolute maximum ratings. Open IC destroyed a failure mode cannot be defined (like Short mode, or Open mode). Therefore physical security countermeasure, like fuse, is to be given when a specified mode to be beyond absolute maximum ratings is considered.
2. Ground potential

GND terminal should be a lowest voltage potential every state.
Please make sure all pins which is over ground even if include transient feature.
3. Setting of heat

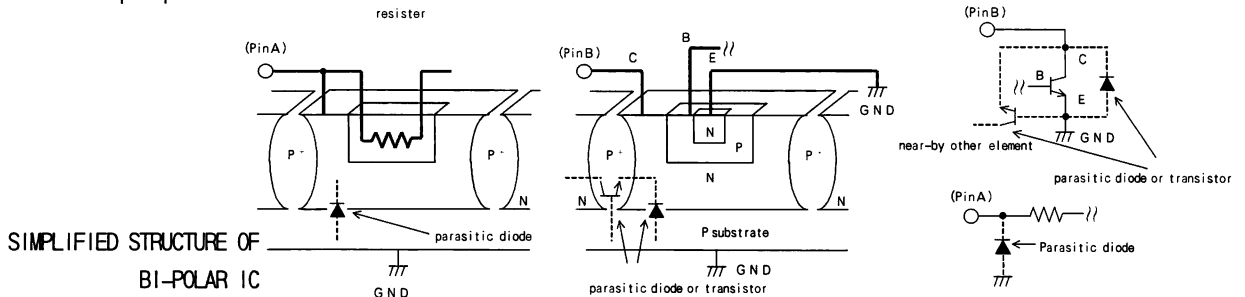
Use a setting of heat that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions..
4. Short Circuit between Terminal and Soldering

Don' t short-circuit between Output pin and V_{DD} pin, Output pin and GND pin, or V_{DD} pin and GND pin. When soldering the IC on circuit board, please be unusually cautious about the orientation and the position of the IC. When the orientation is mistaken the IC may be destroyed.
5. Electromagnetic Field

Mal-function may happen when the device is used in the strong electromagnetic field.
6. Ground wiring patterns

When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the application's reference point so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring patterns of any external components.
7. This IC is a monolithic IC which has P+ isolation in the P substrate and between the various pins.

A P-N junction is formed from this P layer and the N layer of each pin.
For example, when a resistor and a transistor is connected to a pin.
Parasitic diodes can occur inevitably in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits as well as operation faults and physical damage. Accordingly, you must not use methods by which parasitic diodes operate, such as applying a voltage that is lower than the GND (P substrate) voltage to an input pin.



8. Over current protection circuit

The over-current protection circuits are built in at output, according to their respective current outputs and prevent the IC from being damaged when the load is short-circuited or over-current. But, these protection circuits are effective for preventing destruction by unexpected accident. When it' s in continuous protection circuit moving period don' t use please. And for ability, because this chip has minus characteristic, be careful for heat plan.
9. Built-in thermal circuit

A temperature control circuit is built in the IC to prevent the damage due to overheat.
Therefore, all the outputs are turned off when the thermal circuit works and are turned on when the temperature goes down to the specified level.
10. Testing on application boards

When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Ground the IC during assembly steps as an antistatic measure, and use similar caution when transporting or storing the IC. Always turn the IC's power supply off before connecting it to or removing it from a jig or fixture during the inspection process.

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